

N-Channel Super Junction Power MOSFET $\ensuremath{\,\mathrm{IV}}$

General Description

The series of devices use advanced trench gate super junction technology and design to provide excellent R_{DS(ON)} with low gate charge. This super junction MOSFET fits the industry's AC-DC SMPS requirements for PFC, AC/DC power conversion, and industrial power applications.

Features

- Optimized body diode reverse recovery performance
- ●Low on-resistance and low conduction losses
- Small package
- ●Ultra Low Gate Charge cause lower driving requirements
- ●100% Avalanche Tested
- ●ROHS compliant

Application

- Power factor correction (PFC)
- Switched mode power supplies(SMPS)
- Uninterruptible Power Supply (UPS)
- LLC Half-bridge

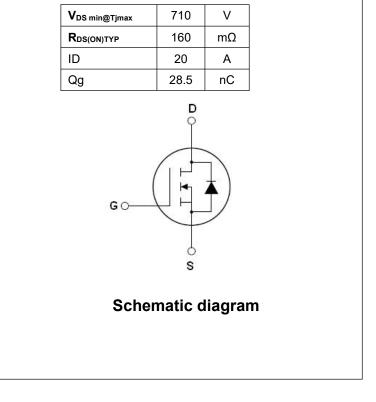
Package Marking And Ordering Information

Device	Device Package	Marking
NCE65N180F	TO-220F-3L	NCE65N180F

Table 1. Absolute Maximum Ratings (Tc=25℃)

Parameter	Symbol	Value	Unit
Drain-Source Voltage (VGS=0V)	Vds	650	V
Gate-Source Voltage (VDS=0V) AC (f>1 Hz)	Vgs	±30	V
Gate-Source Voltage (VDS=0V) DC	Vgs	±20	V
Continuous Drain Current at Tc=25°C	I _{D (DC)}	20	A
Continuous Drain Current at Tc=100°C	I _{D (DC)}	14	A
Pulsed drain current (Note 1)	I _{DM (pluse)}	60	A
Maximum Power Dissipation(Tc=25°C)	PD	33.9	W
Derate above 25°C		0.226	W/°C
Avalanche current ^(Note 1)	I _{AS}	6	A
Drain Source voltage slope, V _{DS} ≤480 V,	dv/dt	50	V/ns
Reverse diode dv/dt, $V_{DS} \leq 480 \text{ V}, I_{SD} \leq I_D$	dv/dt	50	V/ns
Operating Junction and Storage Temperature Range	TJ,TSTG	-55+175	°C

* limited by maximum junction temperature



TO-220F



Table 2. Thermal Characteristic

Parameter	Symbol	Value	Unit
Thermal Resistance, Junction-to-Case (Maximum)	R _{thJC}	4.42	°C /W
Thermal Resistance, Junction-to-Ambient (Maximum)	R _{thJA}	62	°C /W

Table 3. Electrical Characteristics (TA=25°C unless otherwise noted)

Parameter	Symbol	Condition	Min	Тур	Max	Unit
On/off states						
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V I _D =250µA	650			V
Zero Gate Voltage Drain Current(Tc=25°C)	I _{DSS}	V _{DS} =650V,V _{GS} =0V			1	μA
Zero Gate Voltage Drain Current(Tc=125℃)	I _{DSS}	V _{DS} =650V,V _{GS} =0V			100	μA
Gate-Body Leakage Current	I _{GSS}	V _{GS} =±20V,V _{DS} =0V			±100	nA
Gate Threshold Voltage	V _{GS(th)}	V _{DS} =V _{GS} ,I _D =250µA	3	3.5	4	V
Drain-Source On-State Resistance	R _{DS(ON)}	V _{GS} =10V, I _D =10A		160	180	mΩ
Dynamic Characteristics						
Input Capacitance	Clss			1550	1950	pF
Output Capacitance	Coss	V _{DS} =50V,V _{GS} =0V, F=1.0MHz		60		pF
Reverse Transfer Capacitance	C _{rss}	F=1.0MHZ		5		pF
Total Gate Charge	Qg			28.5		nC
Gate-Source Charge	Qgs	V _{DS} =480V,I _D =10.5A,		11.7		nC
Gate-Drain Charge	Q _{gd}	V _{GS} =10V		5		nC
Gate plateau voltage	Vgp			5.7		V
Intrinsic gate resistance	Rg	f = 1 MHz open drain		2		Ω
Switching times	L.					
Turn-on Delay Time	t _{d(on)}			32		nS
Turn-on Rise Time	tr	V _{DD} =380V,I _D =10A,		18		nS
Turn-Off Delay Time	t _{d(off)}	R _G =1.7Ω,V _{GS} =10V		90		nS
Turn-Off Fall Time	t _f			8		nS
Source- Drain Diode Characteristics						
Source-drain current(Body Diode)	I _{SD}	T OF O			20	Α
Pulsed Source-drain current(Body Diode)	I _{SDM}	T _c =25°C			60	А
Forward On Voltage	V _{SD}	Tj=25°C,I _{SD} =20A,V _{GS} =0V		0.9	1.2	V
Reverse Recovery Time	t _{rr}	T: 0500 L 101		300		nS
Reverse Recovery Charge	Qrr	Tj=25°C,I⊧=10A,		4.5		uC
Peak Reverse Recovery Current	Irrm	di/dt=100A/µs		30		Α

Notes 1.Repetitive Rating: Pulse width limited by maximum junction temperature

2. Tj=25°C,VDD=50V,VG=10V, R_G=25 Ω



NCE65N180F

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS (curves)

Figure1. Safe operating area

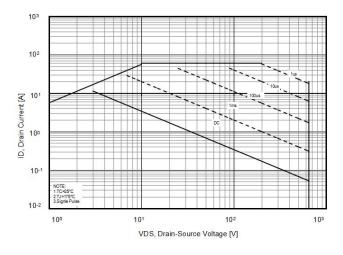


Figure3. Transfer characteristics

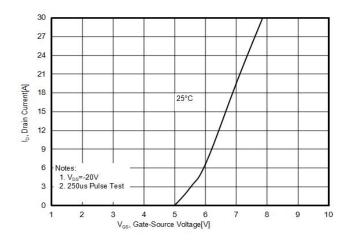


Figure 5. RDS(ON) vs Junction Temperature

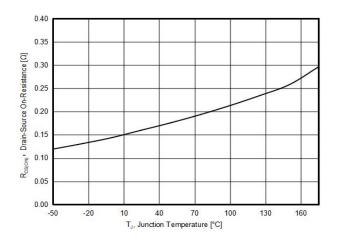


Figure2. Capacitance

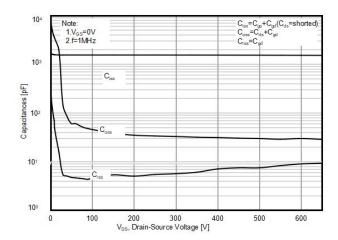


Figure4. Output characteristics

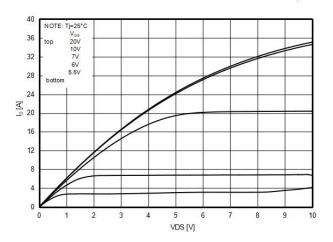


Figure6. BV_{DSS} vs Junction Temperature

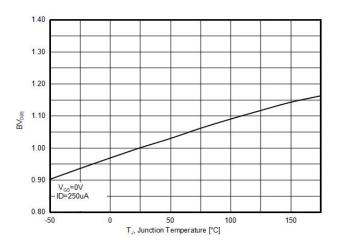




Figure7. Maximum I_D vs Junction Temperature

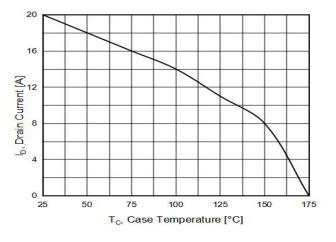


Figure8. Gate charge waveforms

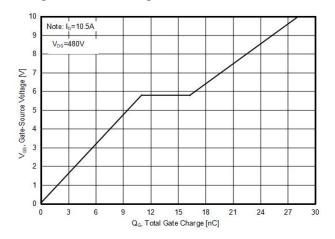


Figure9. Static drain-source on resistance

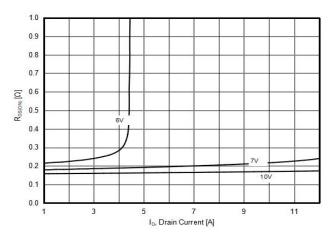
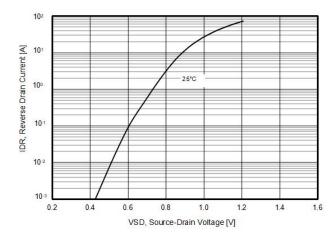


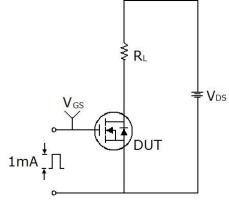
Figure10. Source-Drain Diode Forward Voltage

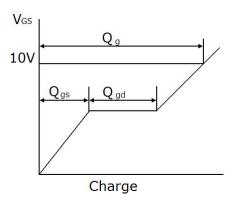




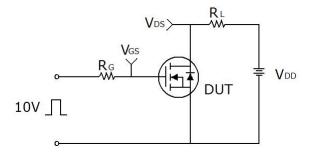
Test circuit

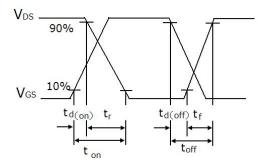
1) Gate charge test circuit & Waveform



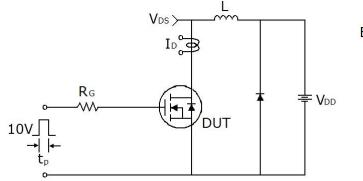


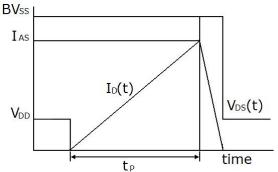
2) Switch Time Test Circuit:





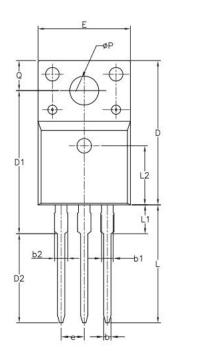
3) Unclamped Inductive Switching Test Circuit & Waveforms

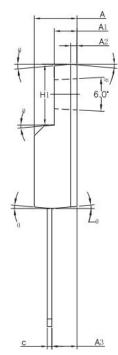






TO-220F-3L-P Package Information





Symbol	Dimensions In Millimeters		Dimensions In Inches		
	Min.	Max.	Min.	Max.	
А	4.50	4.83	0.177	0.190	
A1	2.34	2.74	0.092	0.108	
A2	0.70	REF	0.70 REF		
A3	2.56	2.93	0.101	0.115	
b1	1.18	1.38	0.046	0.054	
b2		1.47		0.058	
с	0.45	0.60	0.018	0.024	
D	15.67	16.07	0.617	0.633	
D1	15.55	15.95	0.612	0.628	
D2	9.60	10.00	0.378	0.394	
E	9.96	10.36	0.392	0.408	
е	2.54 BSC		2.54 BSC		
H1	6.48	6.88	0.255	0.271	
L	12.68	13.28	0.499	0.523	
L1		3.50		0.138	
L2	6.5 REF		6.5 REF		
ΦΡ	3.08	3.28	0.121	0.129	
Q1	3.20	3.40	0.126	0.134	



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